

TC0308A

LTCC

Description

TC0308A is a pure Ag via fill which provides excellent compatibility with HeraLock® HL2000 and Clad CT800 during the cofiring process. After firing it results in a dense filled via with minimal posting.

Key Features

- Low resistivity
- Compatible with HeraLock® HL2000
- Minimal posting

Typical Properties

Viscosity	300-600 KcpsCone and Plate 25/1 cone at 0.052 mm gap at 10 sec-1, 25 °C
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Metal	Ag
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Recommended Processing Guide

Process Temperature (TDS)	See HeraLock® HL2000 data sheet
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